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(12) **United States Design Patent**
Dulai et al.

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(45) **Date of Patent:** ** **Aug. 17, 2004**

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(54) **HIGH DENSITY INTERCONNECTION DEVICE**

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(73) Assignee: **ATI Technologies Inc.**, Ontario (CA)

(**) Term: **14 Years**

(21) Appl. No.: **29/152,841**

(22) Filed: **Dec. 28, 2001**

(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/133**

(58) **Field of Search** D13/133, 147, D13/146; 439/578, 579, 660, 610, 638, 639

(56) **References Cited**

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Primary Examiner—Philip S. Hyder

(74) *Attorney, Agent, or Firm*—Vedder, Price, Kaufman & Kammholz, P.C.

(57) **CLAIM**

The ornamental design of a high density interconnection device, as shown and described.

DESCRIPTION

FIG. **1** is a rear perspective view illustrating a high density interconnection device in accordance with one embodiment of the invention.

FIG. **2** is a front perspective view of the high density interconnection device of FIG. **1**.

FIG. **3** is a front elevation view of the high density interconnection device of FIG. **1**.

FIG. **4** is a rear elevation view of the high density interconnection device of FIG. **1**.

FIG. **5** is a first side elevation view of the high density interconnection device of FIG. **1**.

FIG. **6** is a second side elevation view of the high density interconnection device of FIG. **1**.

FIG. **7** is a top plan view of the high density interconnection device of FIG. **1**.

FIG. **8** is a bottom plan view of the high density interconnection device of FIG. **1**.

FIG. **9** is a rear perspective view illustrating a high density interconnection device in accordance with another embodiment of the invention.

FIG. **10** is a front perspective view of the high density interconnection device of FIG. **9**.

FIG. **11** is a front elevation view of the high density interconnection device of FIG. **9**.

FIG. **12.** is a rear elevation view of the high density interconnection device of FIG. **9**.

FIG. **13** is a first side elevation of the high density interconnection device of FIG. **9**.

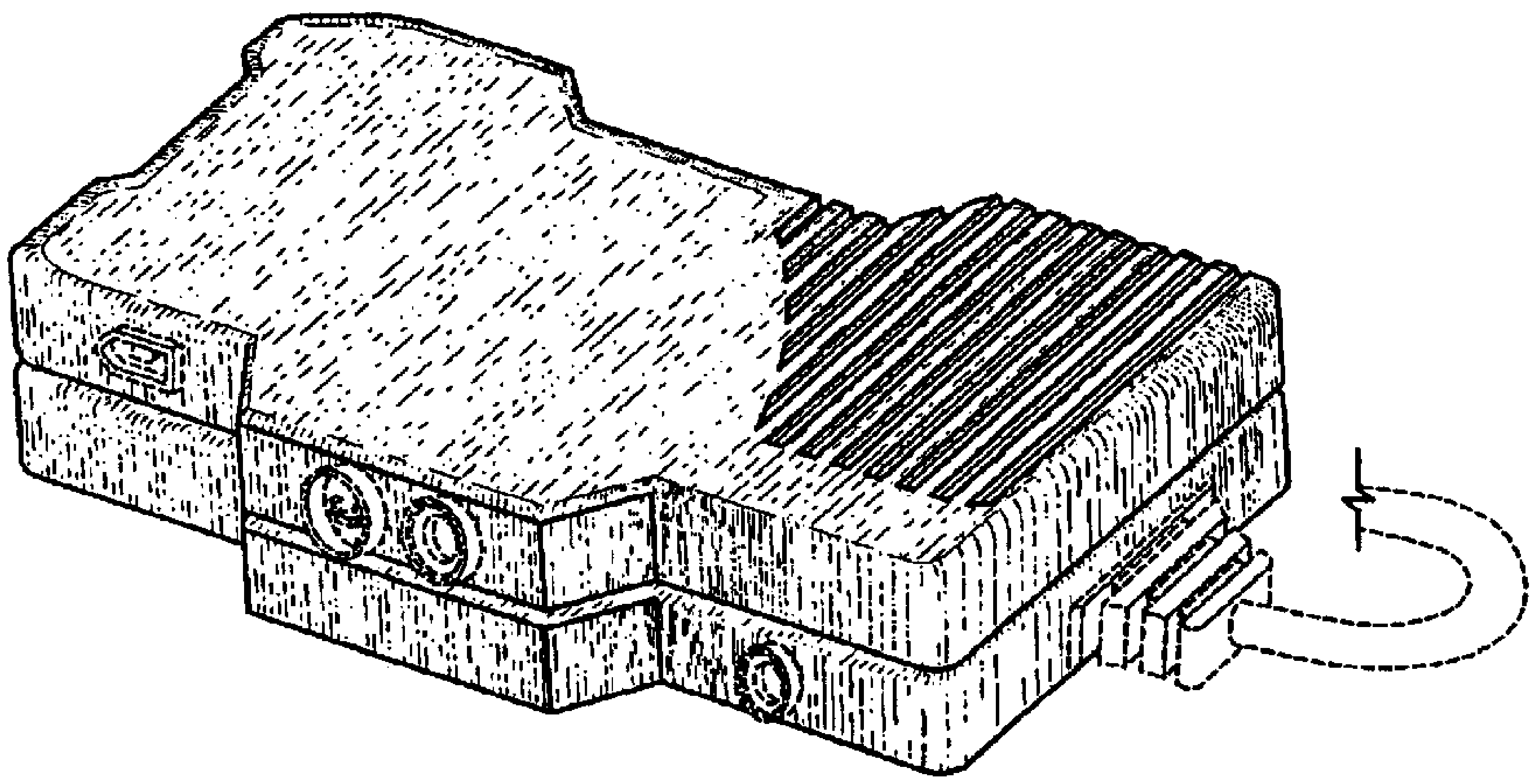
FIG. **14** is a second side elevation view of the high density interconnection device of FIG. **9**.

FIG. **15** is a top plan view of the high density interconnection device of FIG. **9**; and,

FIG. **16** is a bottom plan view of the high density interconnection device of FIG. **9**.

The broken line portions of the disclosure are for illustrative purposes only and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



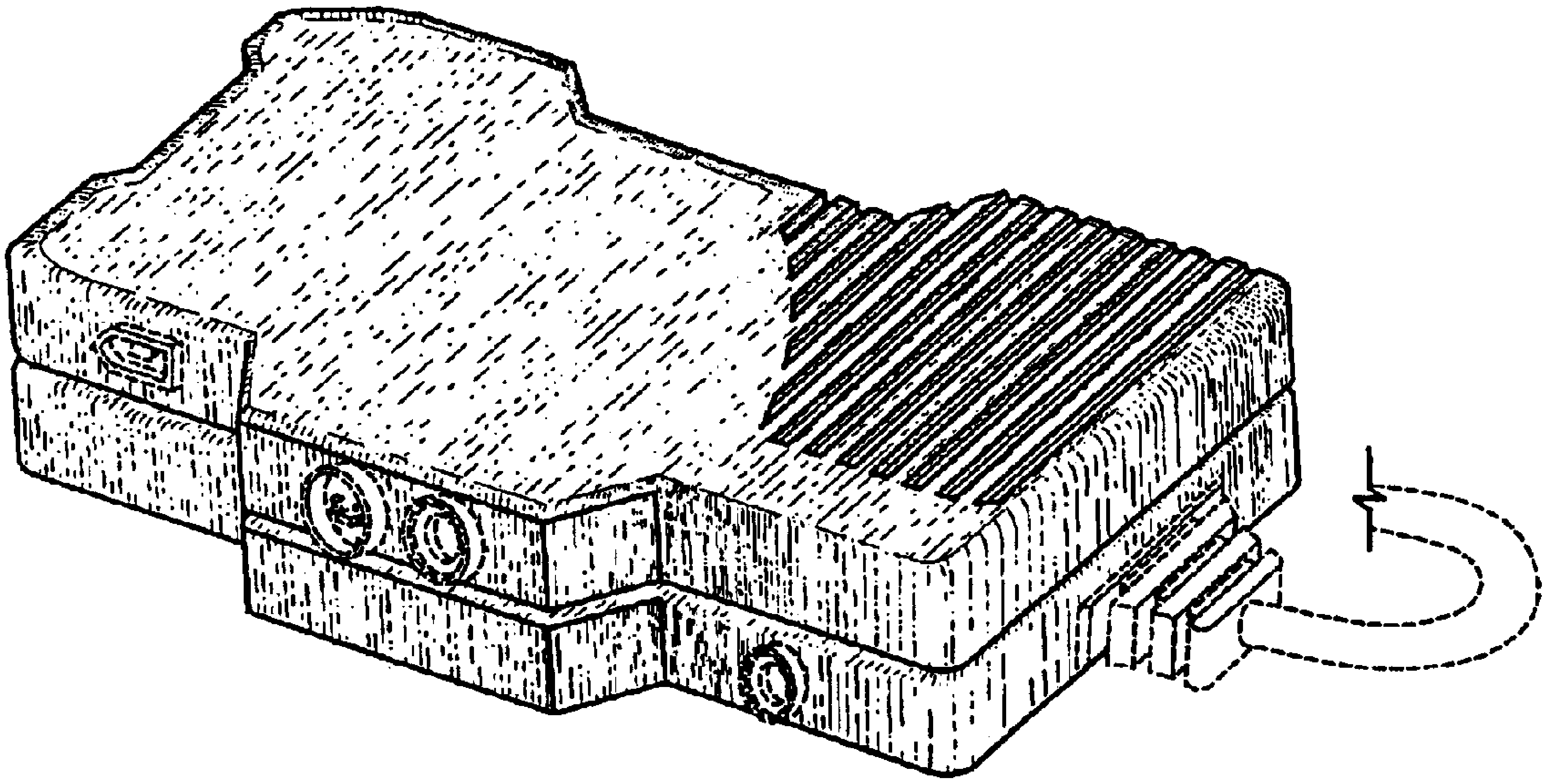


FIG. 1

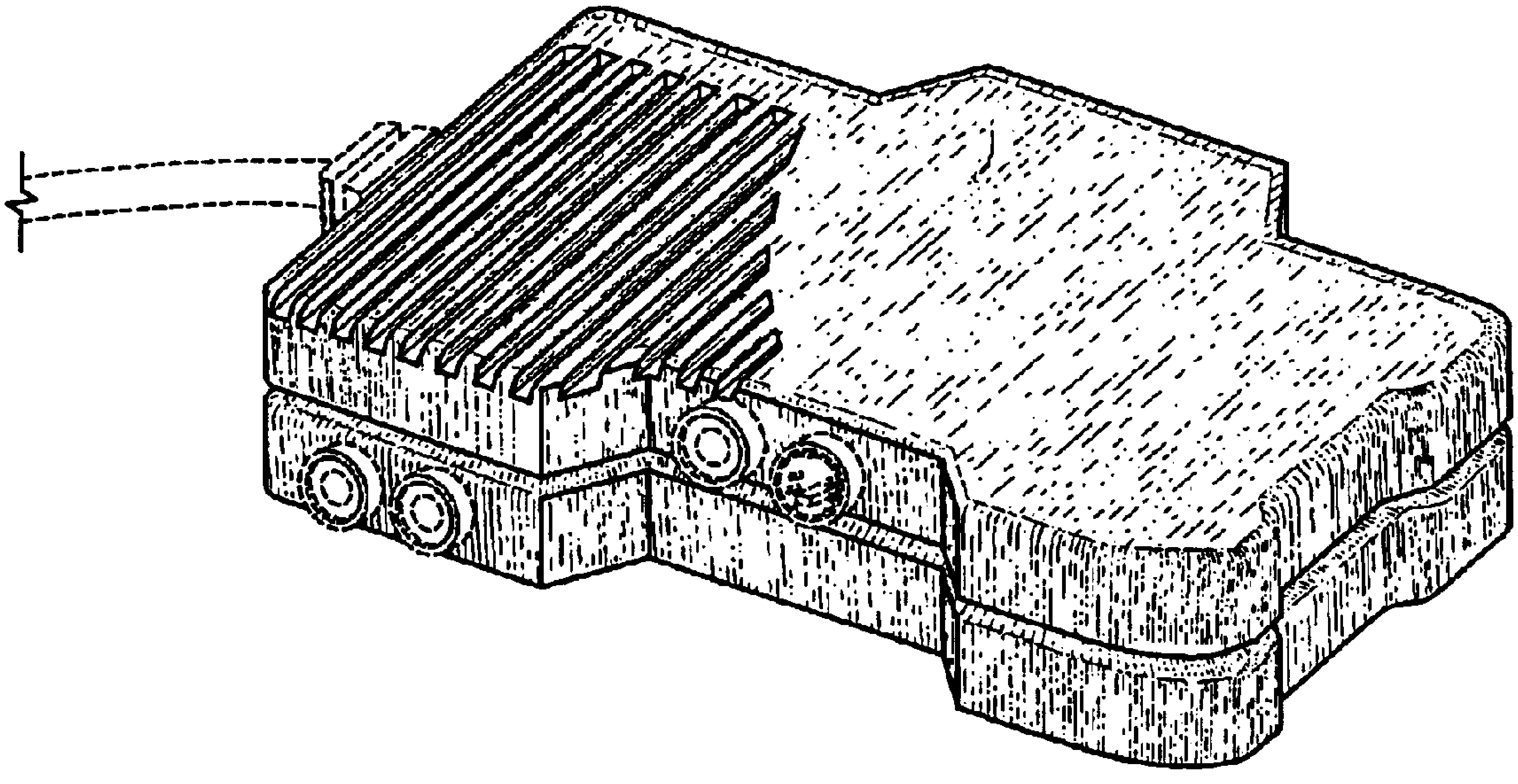


FIG. 2

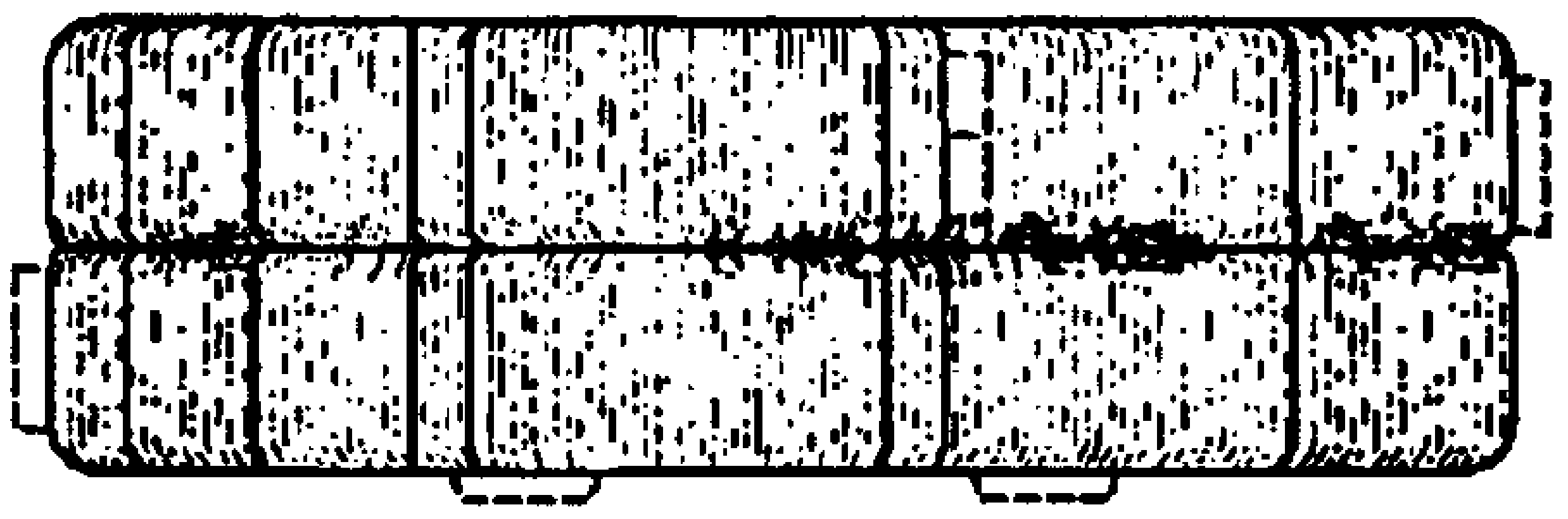


FIG. 3

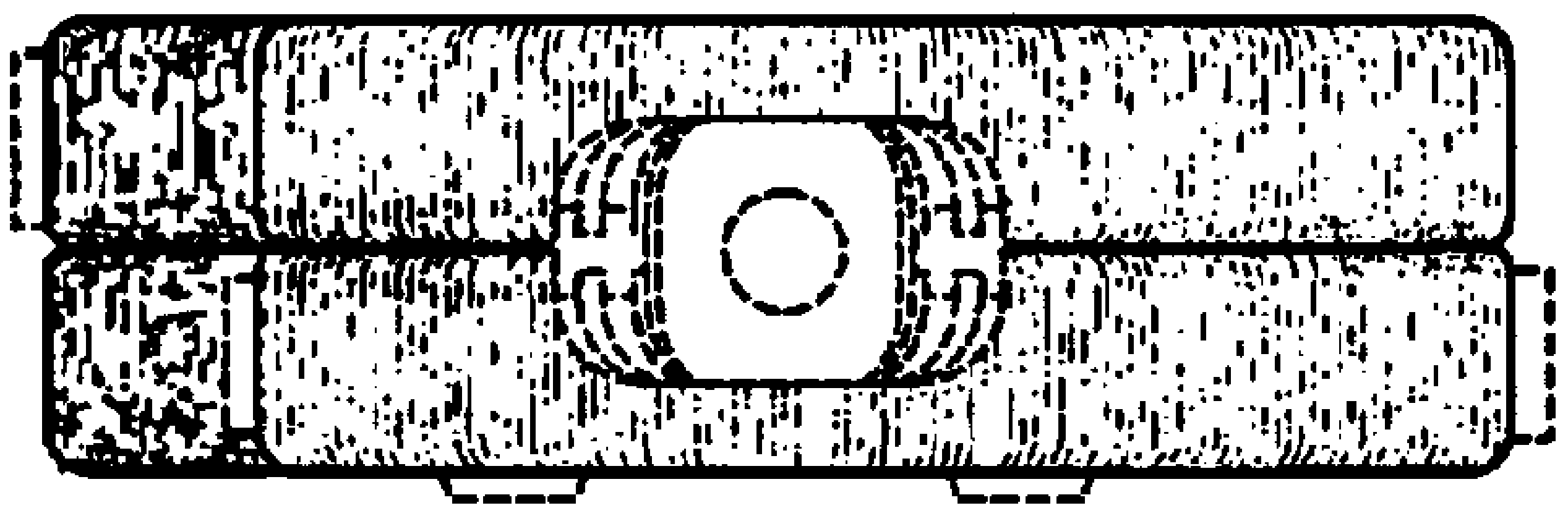


FIG. 4

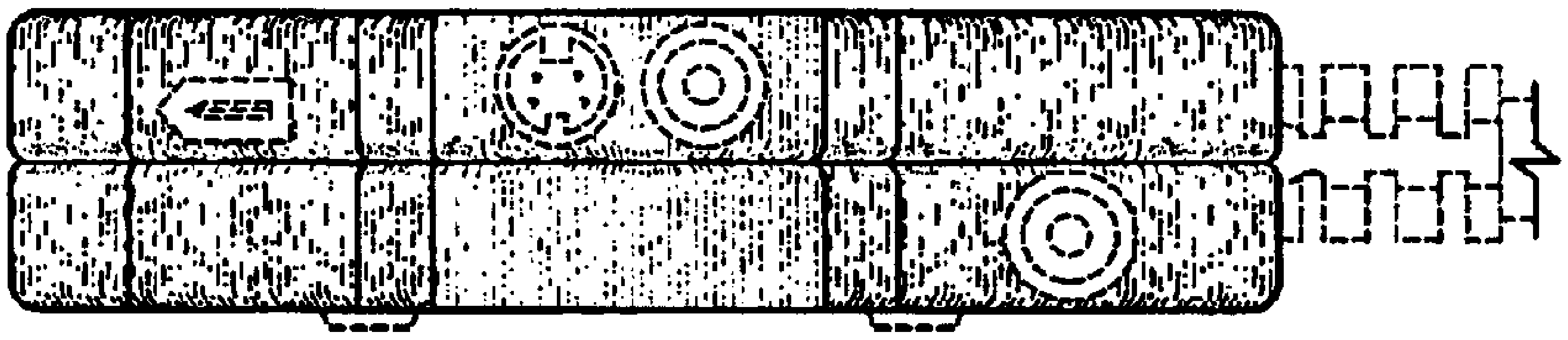


FIG. 5

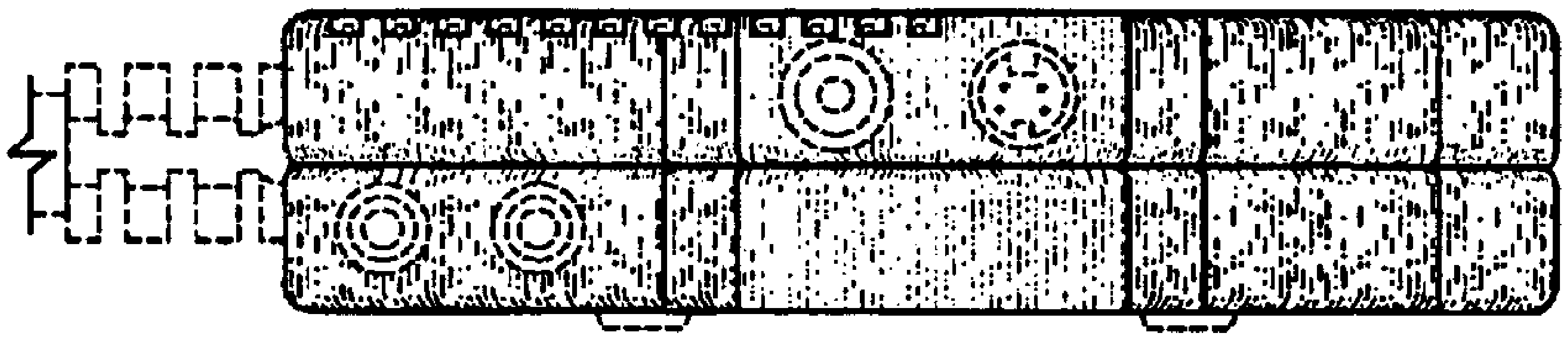


FIG. 6

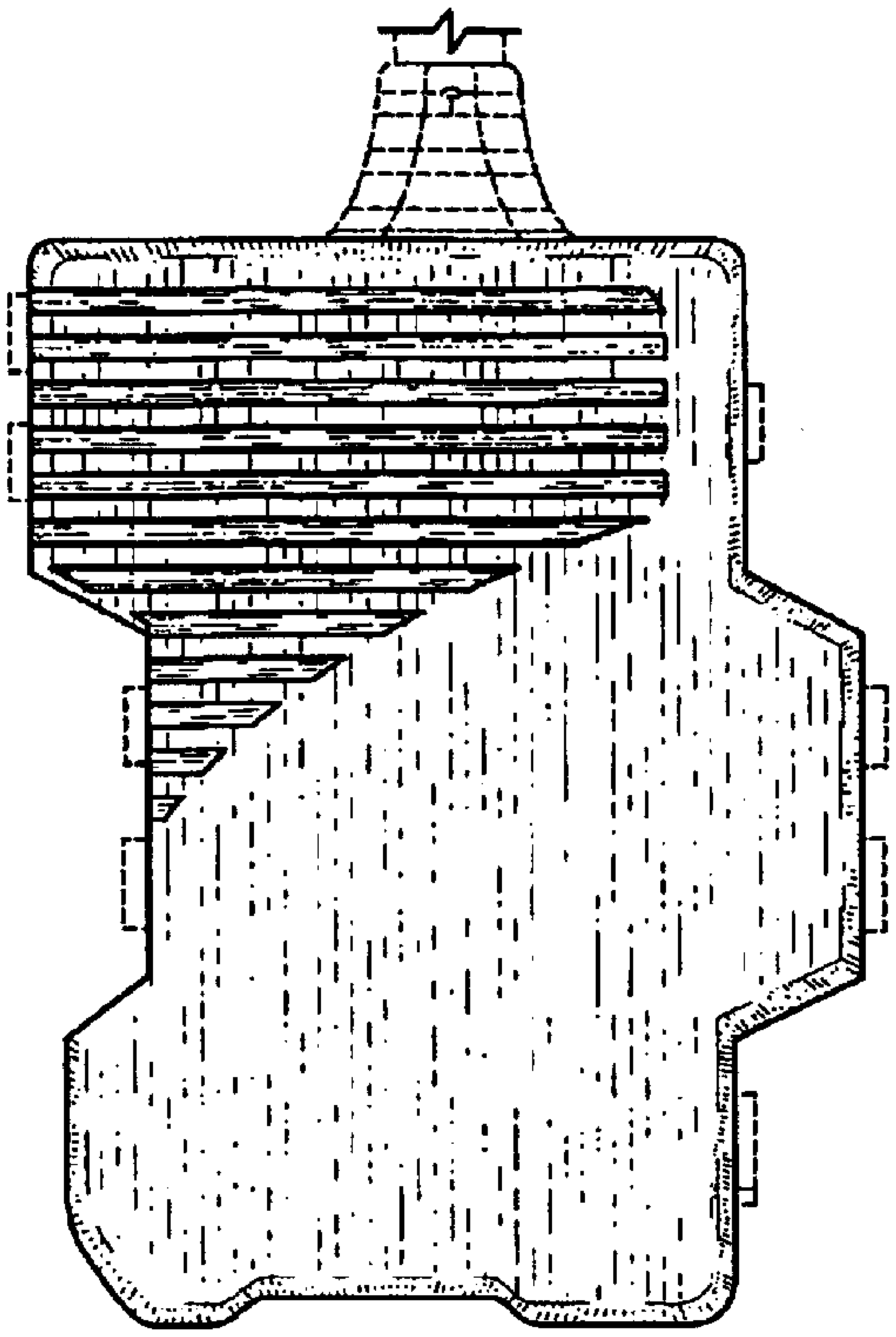


FIG. 7

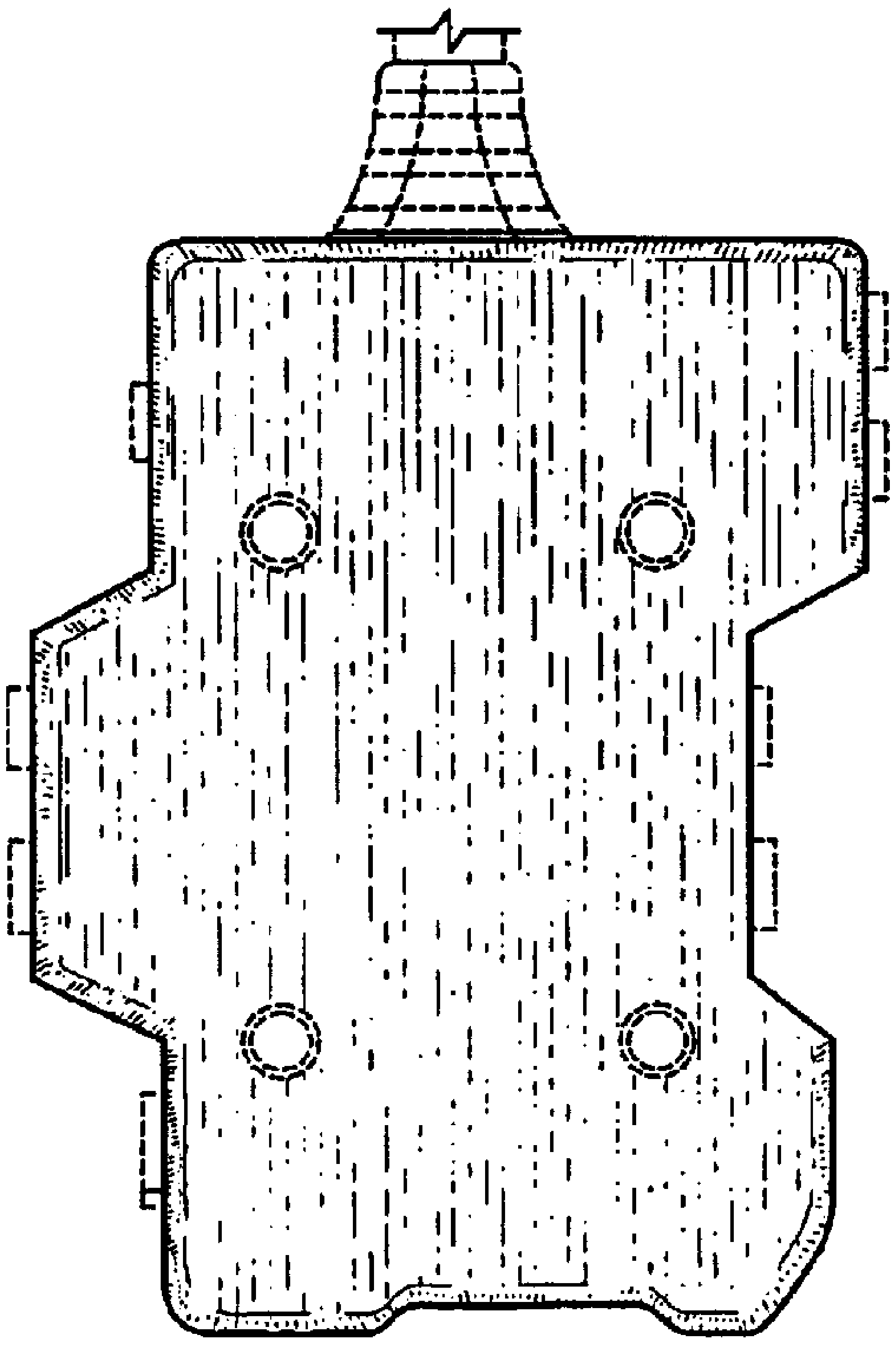


FIG. 8

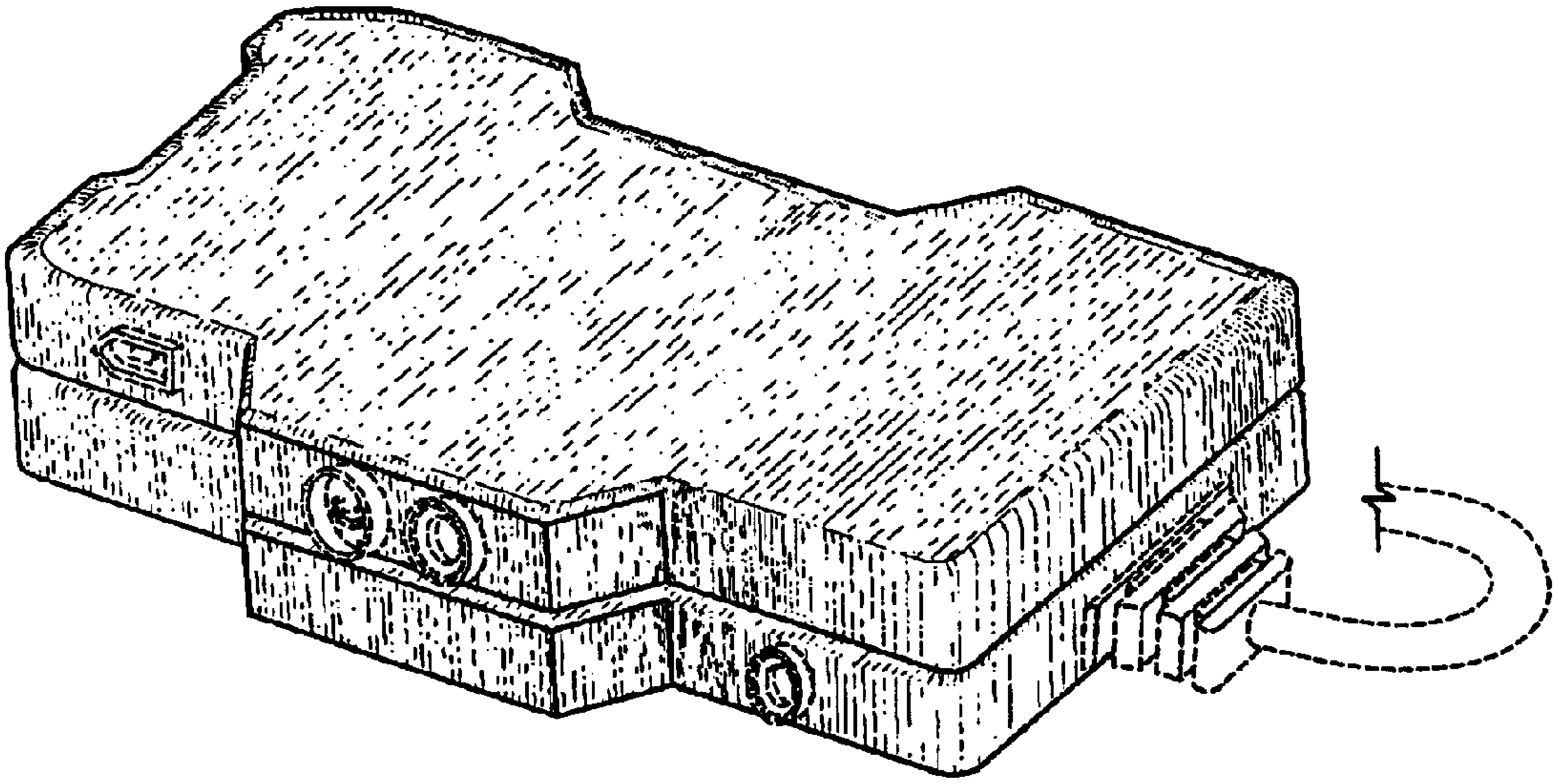


FIG. 9

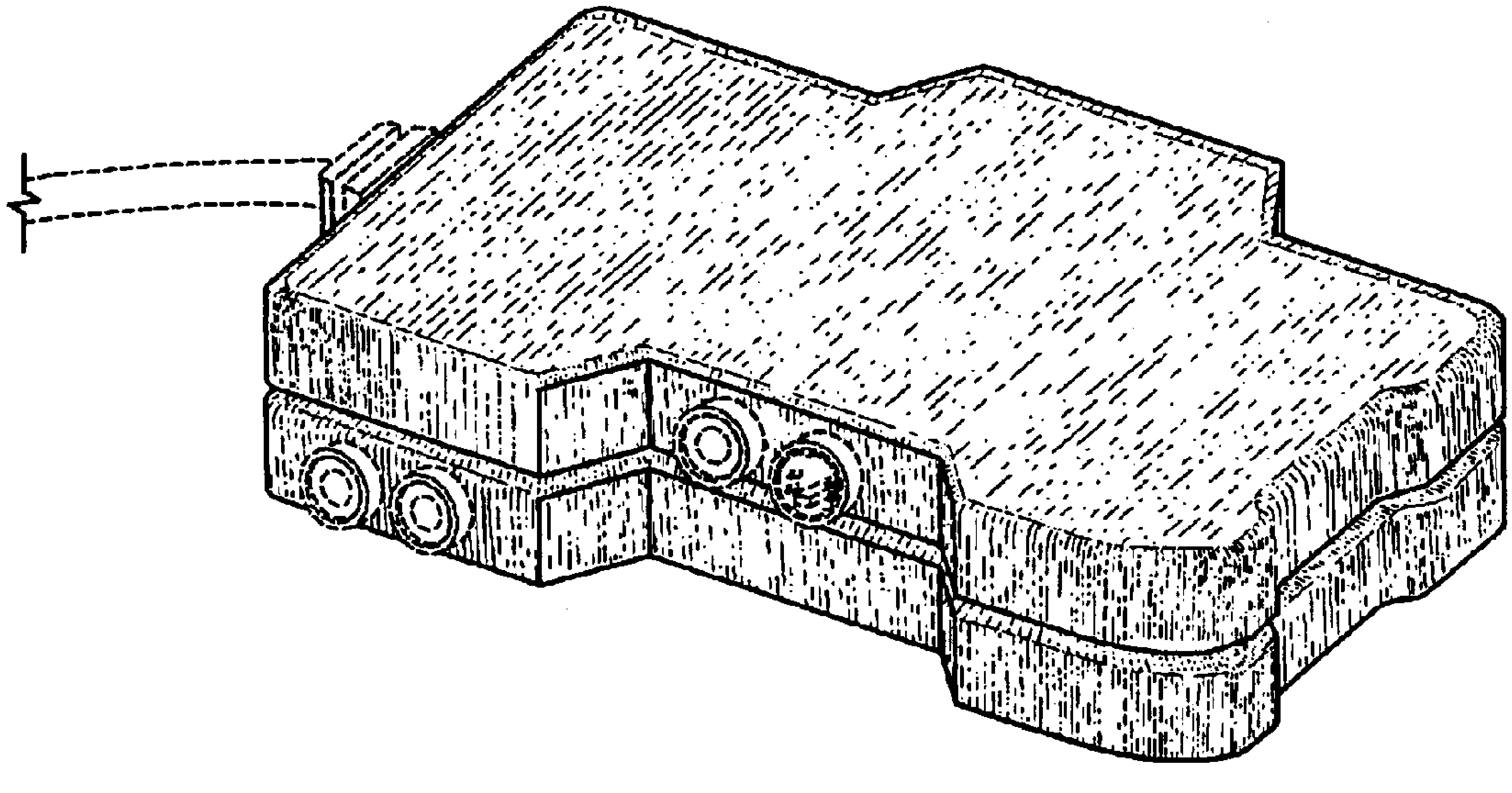


FIG. 10

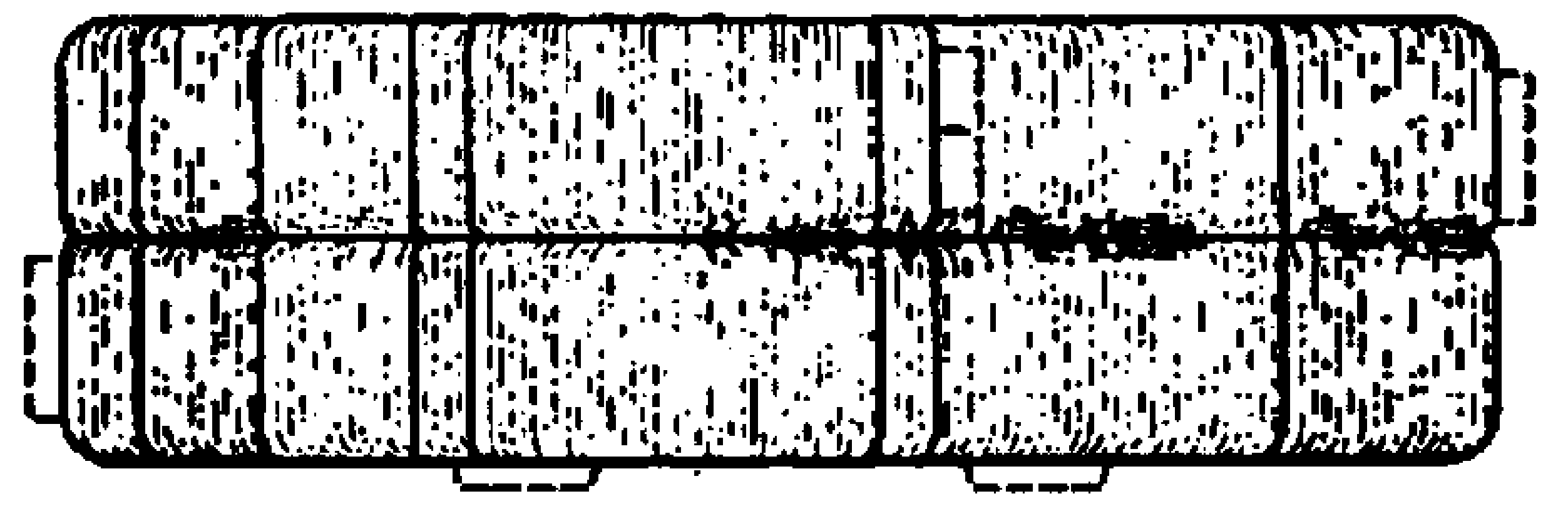


FIG. 11

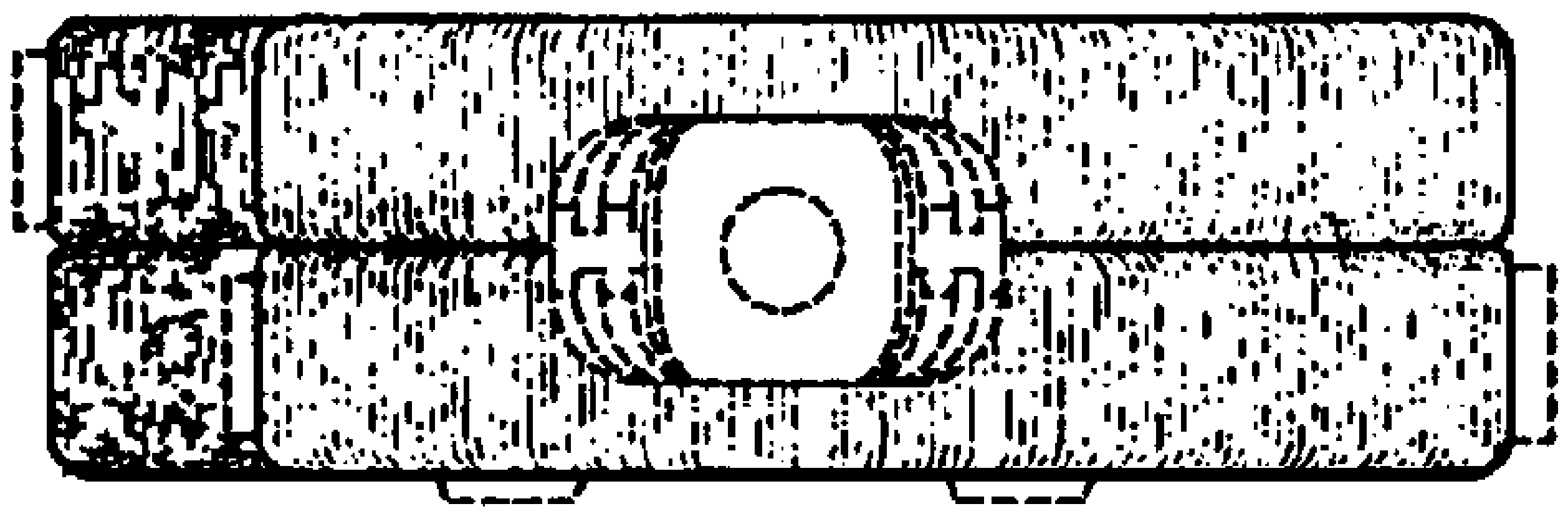


FIG. 12

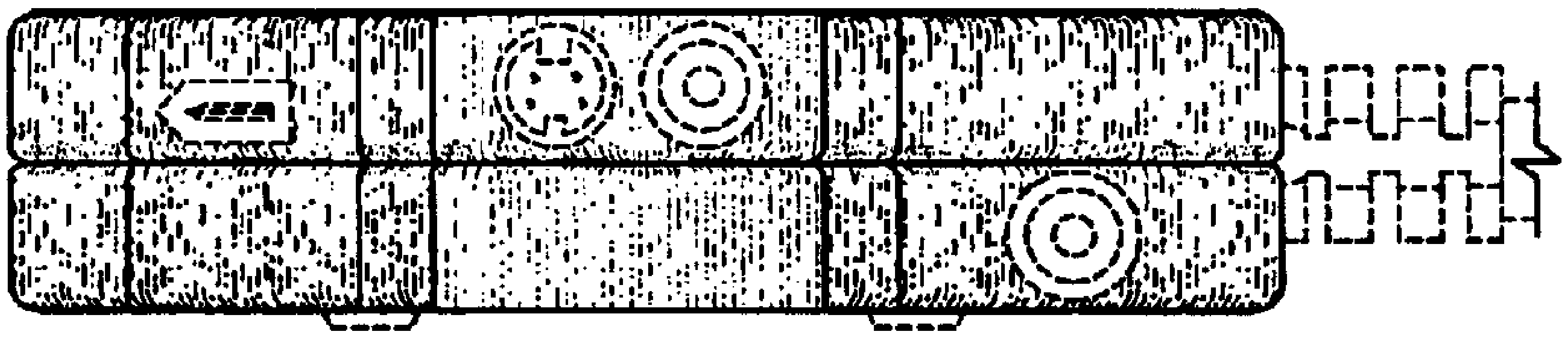


FIG. 13

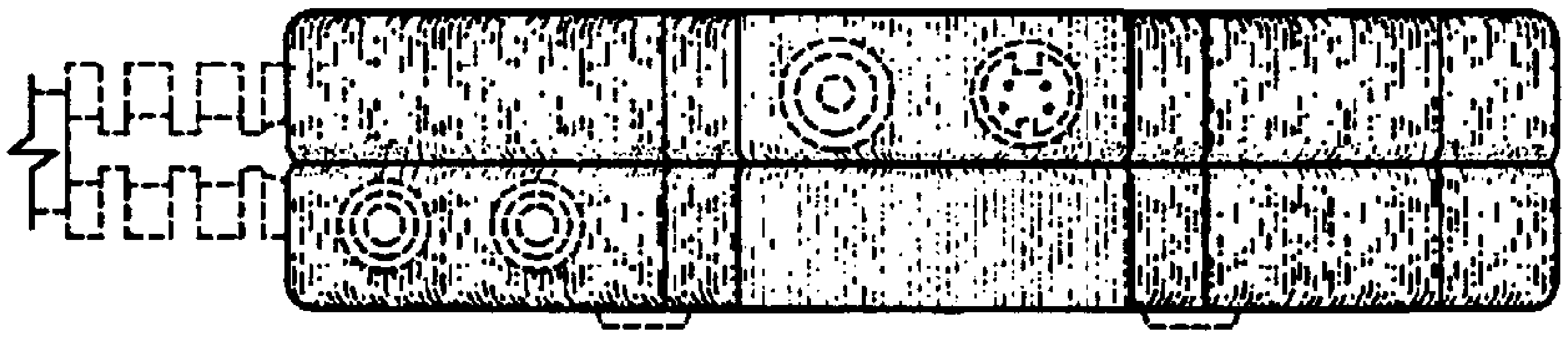


FIG. 14

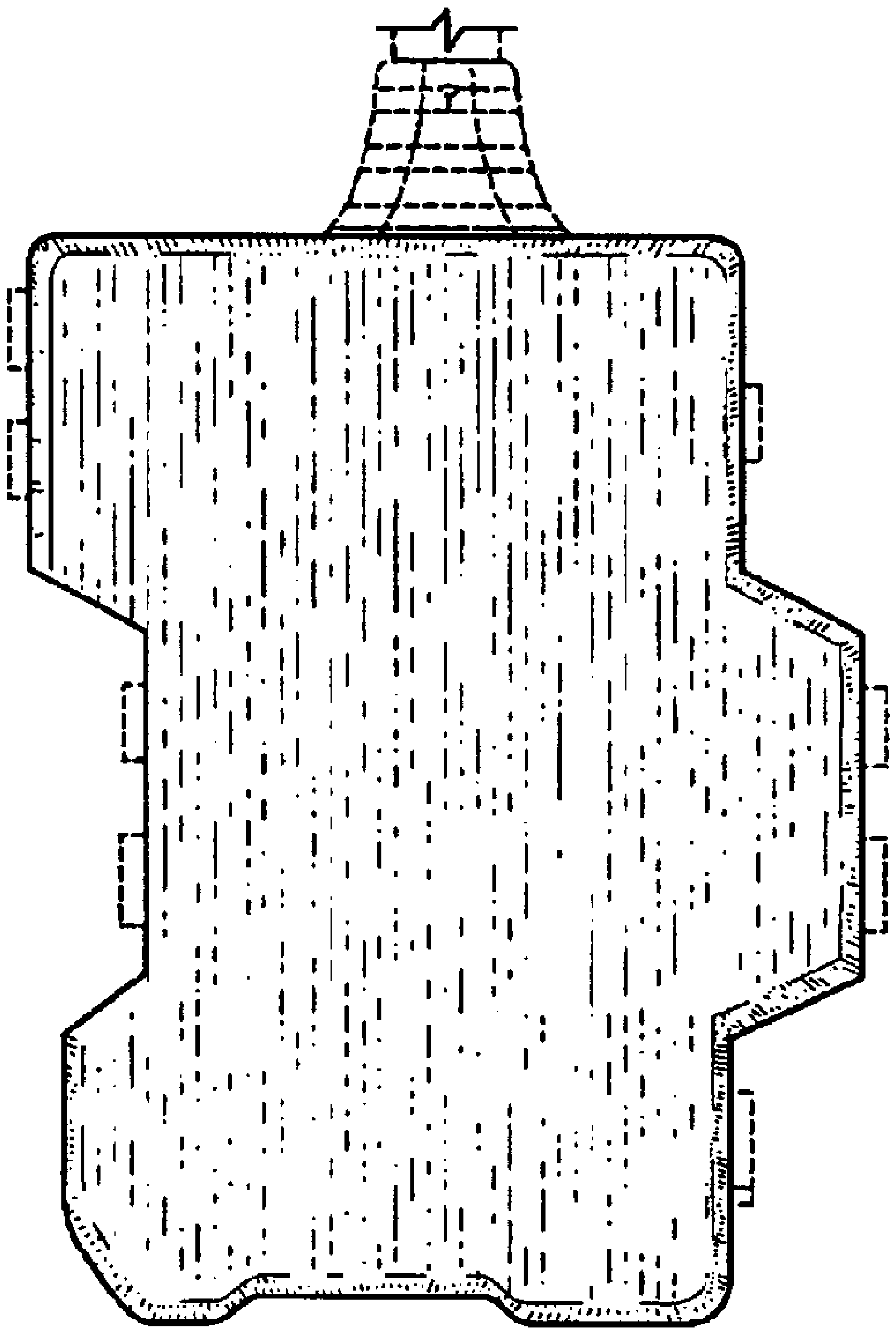


FIG. 15

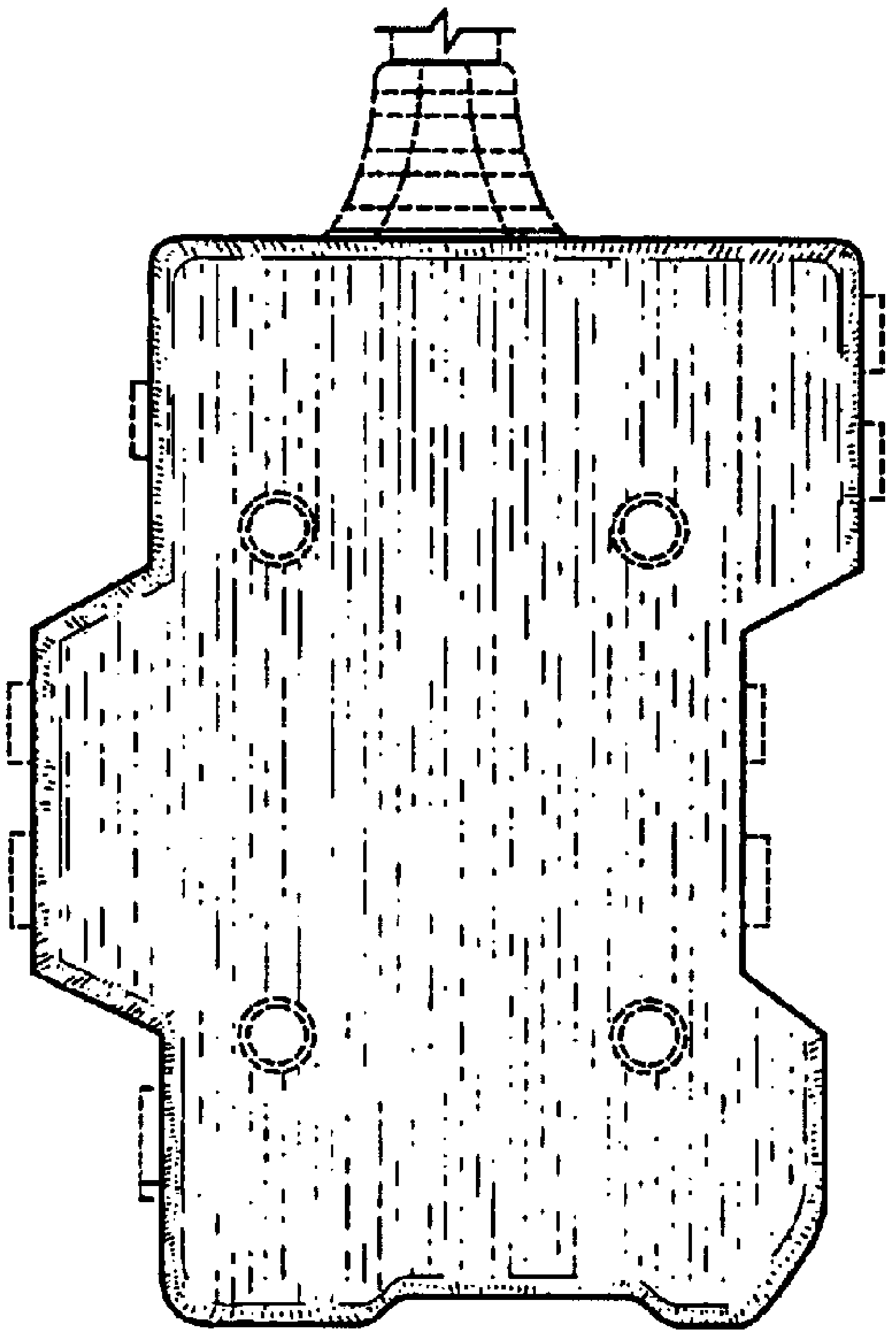


FIG. 16